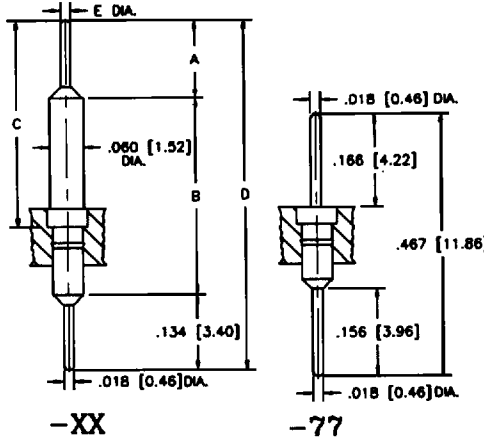


SERIES 110 DIP HEADER: BOARD TO BOARD CONNECTOR (OPEN FRAME)

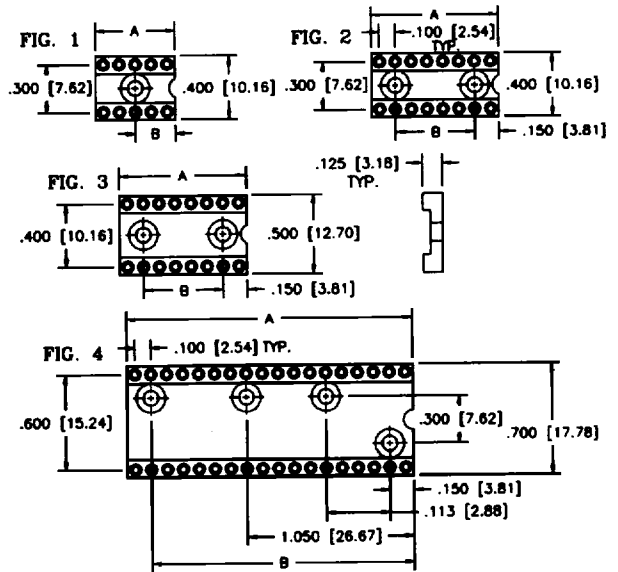
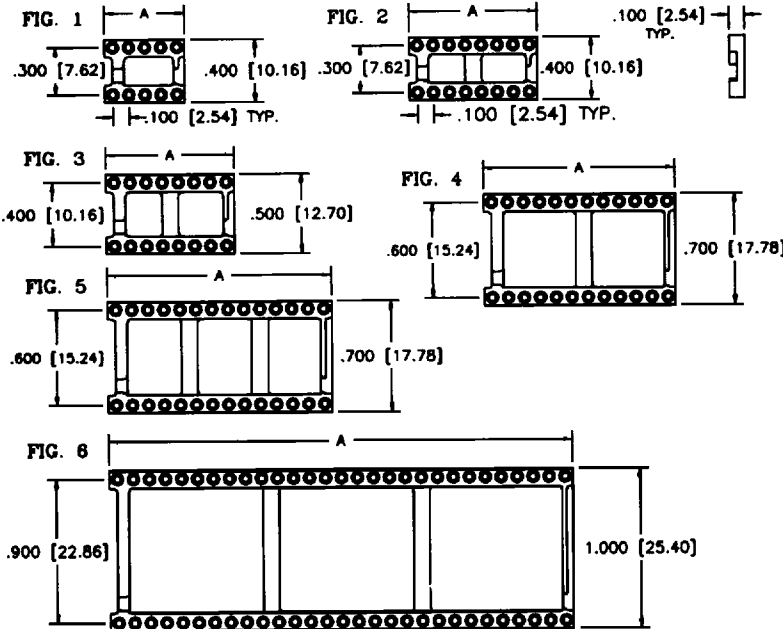
210 DIP HEADER: BOARD TO BOARD CONNECTOR (SOLID FRAME)

SERIES 110 OPEN FRAME WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	16	.800 [20.32]	416
	22	1.100 [27.94]	422
	24	1.200 [30.48]	424
FIG. 4	24	1.200 [30.48]	624
FIG. 5	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640
	48	2.400 [60.96]	648
FIG. 6	50	2.500 [63.50]	950
	52	2.600 [66.04]	952
	64	3.200 [81.28]	964

TERM.	A	B	C	D	E
-56	.184 [4.68]	.583 [14.82]	.630 [16.00]	.902 [22.90]	.026 [0.65]
-58	.140 [3.56]	.350 [8.89]	.390 [9.91]	.624 [15.85]	.018 [0.46]
-59	.140 [3.56]	.457 [11.61]	.479 [12.17]	.731 [18.57]	.018 [0.46]



SERIES 210 SOLID FRAME WAFER CHART				
	PIN	DIM "A"	DIM "B"	
FIG. 1	6	.300 [7.62]	.150 [3.81]	306
	8	.400 [10.16]	.200 [5.08]	308
	10	.500 [12.70]	.250 [6.35]	310
FIG. 2	14	.700 [17.78]	.400 [10.16]	314
	16	.800 [20.32]	.500 [12.70]	316
	18	.900 [22.86]	.600 [15.24]	318
	20	1.000 [25.40]	.700 [17.78]	320
	24	1.200 [30.48]	.900 [22.86]	324
	16	.800 [20.32]	.500 [12.70]	416
FIG. 3	22	1.100 [27.94]	.800 [20.32]	422
	24	1.200 [30.48]	.900 [22.86]	424
	24	1.200 [30.48]		624
FIG. 4	28	1.400 [35.56]		628
	30	1.500 [38.10]		630
	32	1.600 [40.64]		632
	36	1.800 [45.72]	1.650 [41.91]	636
	40	2.000 [50.80]	1.650 [41.91]	640



TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED POLYESTER
UL 94V-0 LISTED

TERMINAL BRASS PER ASTM-B16

OPERATING TEMP. -65°C TO +125°C

ORDERING INFORMATION

110-XXX-XX-XXX-B12
210-XXX-XX-XXX-B10

SERIES — LOGO
110: OPEN — INSULATOR MATERIAL
210: SOLID — OTHER MATERIALS AVAILABLE
CONSULT FACTORY

DIP — SPACING — PLATING: TERMINAL
NO. OF PINS — G04: GOLD
TERMINAL STYLE — T: TIN
TL: TIN-LEAD